

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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EPAS ID: PAT3071532

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ZVI OR-BACH	10/09/2014
DEEPAK SEKAR	10/19/2014
BRIAN CRONQUIST	10/08/2014
ISRAEL BEINGLASS	10/18/2014
JAN LODEWIJK DEJONG	10/14/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	Monolithic 3D Inc.
<b>Street Address:</b>	3555 Woodford Drive
<b>City:</b>	San Jose
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95124
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14509288
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Email:</b>	Brian@Monolithic3D.com
<b>Correspondent Name:</b>	BRIAN CRONQUIST
<b>Address Line 1:</b>	3555 WOODFORD DRIVE
<b>Address Line 4:</b>	SAN JOSE, CALIFORNIA 95124
<b>ATTORNEY DOCKET NUMBER:</b>	MONOLITHIC3D-6CON5
<b>NAME OF SUBMITTER:</b>	BRIAN CRONQUIST
<b>SIGNATURE:</b>	/bc/
<b>DATE SIGNED:</b>	10/20/2014
<b>Total Attachments: 5</b>	
source=Monolithic3D_6con5 Assign Zvis#page1.tif	
source=Monolithic3D_6con5 Assign Deepaks#page1.tif	
source=Monolithic3D_6con5 Assign Brians#page1.tif	

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source=MonolithC3D\_6con5 Assign Israels#page1.tif

source=MonolithC3D\_6con5 Assign JLS#page1.tif

**PATENT**

**REEL: 033979 FRAME: 0800**

**ASSIGNMENT**

Whereas, I, **Zvi Or-Bach** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

**Novel 3D Semiconductor Device and Structure**

as described in U.S. Patent Application Serial No. 14/509,288 and filed on October 08, 2014;  
and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

**INVENTOR:**

DATE on 10-9-14

  
\_\_\_\_\_  
(Zvi Or-Bach)  
First Name Middle Initial Last Name

**ASSIGNMENT**

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

**Novel 3D Semiconductor Device and Structure**

as described in U.S. Patent Application Serial No. 14/509,288 and filed on October 08, 2014;  
and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

**INVENTOR:**

DATE on 17<sup>th</sup> Oct 2014

Deepak. C. Sekar  
\_\_\_\_\_  
(Deepak Sekar)  
First Name Middle Initial Last Name

**ASSIGNMENT**

Whereas, I, **Brian Cronquist (hereinafter referred to as Assignor(s)), residing in San Jose, California;** have made a certain invention, and executed United States Patent Application entitled:

**Novel 3D Semiconductor Device and Structure**

as described in U.S. Patent Application Serial No. 14/509,288 and filed on October 08, 2014;  
and

Whereas, **MonolithIC 3D™ Inc.**, a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

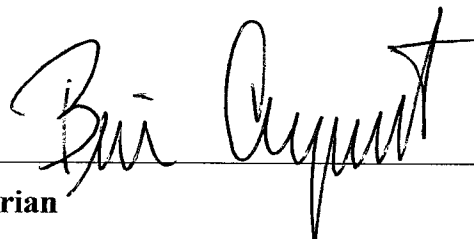
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Signed and Sealed:

**INVENTOR:**

DATE on 8 October 2014

  
\_\_\_\_\_  
(Brian Cronquist)  
First Name Middle Initial Last Name



**ASSIGNMENT**

Whereas, I, **Jan Lodewijk deJong** (hereinafter referred to as Assignor(s)), residing in **San Jose, California**; have made a certain invention, and executed United States Patent Application entitled:

**Novel 3D Semiconductor Device and Structure**

as described in U.S. Patent Application Serial No. 14/509,288 and filed on October 08, 2014;  
and

Whereas, MonolithIC 3D™ Inc., a company located at 3555 Woodford Drive, San Jose, California 95124 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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Signed and Sealed:

**INVENTOR:**

DATE on 10-14-2014

  
\_\_\_\_\_  
(Jan Lodewijk

First Name

Middle Initial

deJong)

Last Name